# DB2J316

### Silicon epitaxial planar type

#### For small current rectification

#### Features

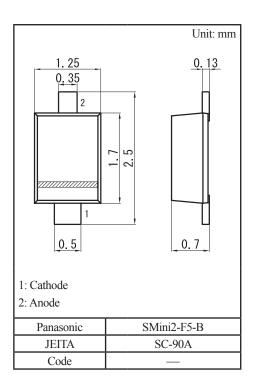
- Short reverse recovery time t<sub>rr</sub>
- Low forward voltage  $V_F$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: C7

#### Packaging

 $DB2J31600L \quad Embossed \ type \ (Thermo-compression \ sealing): \ 3\ 000 \ pcs \ / \ reel \ (standard)$ 

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	30	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V	
Forward current (Average)	I <sub>F(AV)</sub>	100	mA	
Peak forward current	I <sub>FM</sub>	300	mA	
Non-repetitive peak forward surge current *1	I <sub>FSM</sub>	1	А	
Junction temperature	Tj	125	°C	
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	



Note) \*1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

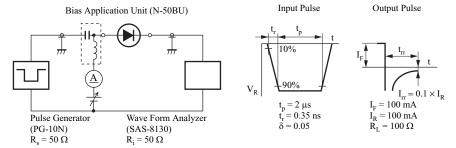
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

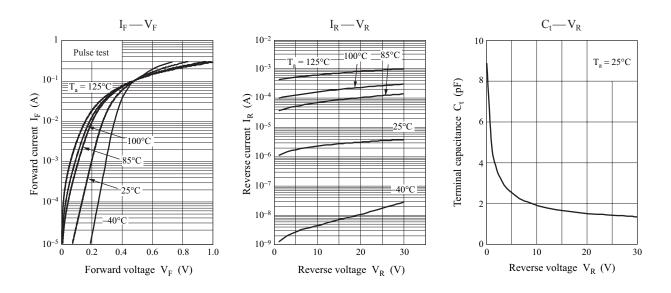
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I <sub>R</sub>	$V_R = 30 V$			15	μΑ
Terminal capacitance	Ct	$V_{R} = 10 V, f = 1 MHz$		2		pF
Reverse recovery time *1	t <sub>rr</sub>	$\begin{split} I_F = I_R = 100 \text{ mA}, \ I_{rr} = 0.1 \times I_R, \\ R_L = 100 \ \Omega \end{split}$		0.8		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

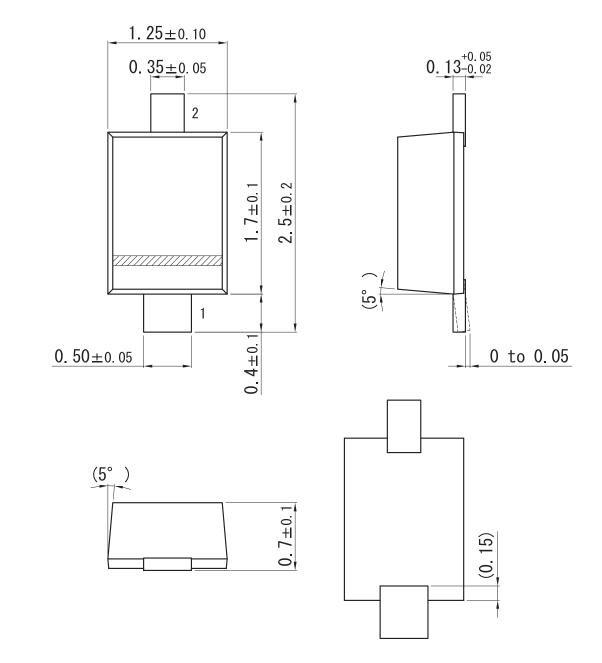
- 3. Absolute frequency of input and output is 250  $\ensuremath{\text{MHz}}$
- \*1: trr measurement circuit



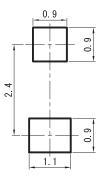


Unit: mm

SMini2-F5-B



Land Pattern (Reference) (Unit: mm)



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